

Appl. No. 09/976,624

R placement section

**Amendments to th Claims**

Claims 1-104 are cancelled.

105. (Currently amended) A method of forming a an insulative material adjacent a conductive electrical component comprising:

providing ~~a mass~~ an initial material adjacent the conductive electrical component, the ~~mass~~ initial material comprising pores having a size and the ~~mass~~ comprising molecules consisting of silicon and carbon;

forming a layer overlying the mass; and

decreasing the dielectric constant of the initial material to form the insulative material by vaporizing a portion of the initial material mass to expand the size of the pores ~~within the mass~~.

Claims 106-110 are cancelled.

111. (Currently amended) The method of Claim 105, further comprising forming a layer over the initial material ~~mass~~ before the vaporizing.

112. (Currently amended) The method of Claim 105, further comprising forming a layer over the initial material ~~mass~~ after the vaporizing.

113. (Previously presented) The method of Claim 105, where the conductive electrical component comprises a pair of conductive lines.

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Replacement section

114. (Previously presented) The method of Claim 113, further comprising forming at least one support member between the pair of conductive lines.

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Claims 115-129 are cancelled.

130. (Currently amended) The method of claim 105 wherein the initial material ~~mass~~ comprises  $\text{SiC}_x$ .

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